NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE2006Y uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =20V,I_D =6A

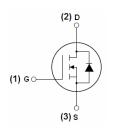
 $R_{DS(ON)}$ <13m Ω @ V_{GS} =4.5V (Typ:10.5m Ω)

 $R_{DS(ON)}$ <18m Ω @ V_{GS} =2.5V (Typ:15m Ω)

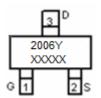
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

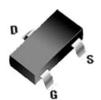
- Power switching application
- Load switching
- Uninterruptible power supply



Schematic diagram



Marking and pin Assignment



SOT-23-3L top view

Package Marking and Ordering Information

	<u> </u>				
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2006Y	NCE2006Y	SOT23-3L	Ø180mm	8mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous	I _D	6	Α
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	4.2	Α
Pulsed Drain Current	I _{DM}	24	Α
Maximum Power Dissipation	P _D	1.5	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	83.3	°C/W

Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V

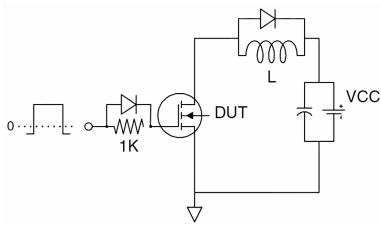
Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.7	1.2	V	
Dunin Course On Otata Basistana		V _{GS} =4.5V, I _D =6A	-	10.5	13	0	
Drain-Source On-State Resistance	$R_{DS(ON)}$	V _{GS} =2.5V, I _D =5A		15	18	mΩ	
Dynamic Characteristics (Note4)							
Input Capacitance	C _{lss}			620		PF	
Output Capacitance	C _{oss}	V_{DS} =10V, V_{GS} =0V, F=1.0MHz		125		PF	
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIMZ		64		PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	4.5	-	nS	
Turn-on Rise Time	t _r	V _{GS} =10V,V _{DS} =10V	-	9.2	-	nS	
Turn-Off Delay Time	t _{d(off)}	$R_L=0.5\Omega,R_G=3\Omega$	-	18.7	-	nS	
Turn-Off Fall Time	t _f		-	3.3	-	nS	
Total Gate Charge	Qg			15		nC	
Gate-Source Charge	Q _{gs}	V _{GS} =10V,V _{DS} =10V,I _D =6A		1.8		nC	
Gate-Drain Charge	Q_gd]		2.8		nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is	-	-	-	6	Α	

Notes:

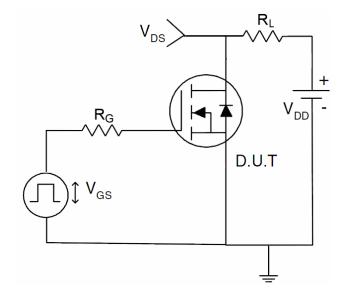
- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, t ≤ 10 sec.
 Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

Test circuit

1) Gate charge test Circuit:



2) Switch Time Test Circuit:



Typical Electrical and Thermal Characteristics (Curves)

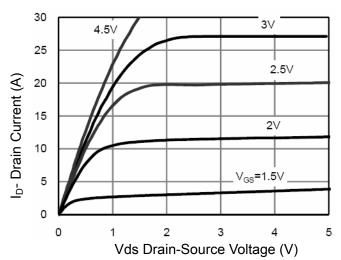


Figure 1 Output Characteristics

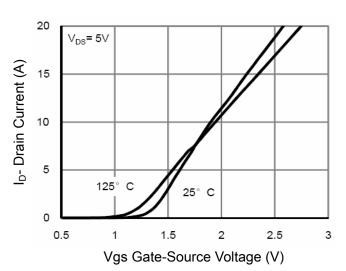


Figure 2 Transfer Characteristics

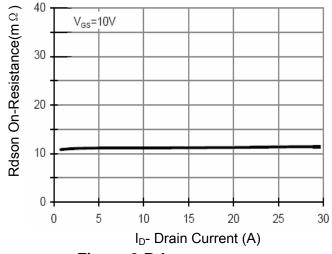


Figure 3 Rdson- Drain Current

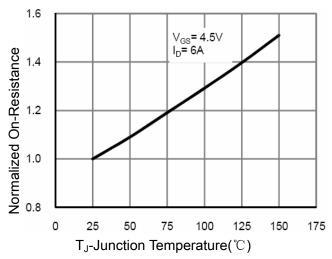


Figure 4 Rdson-Junction Temperature

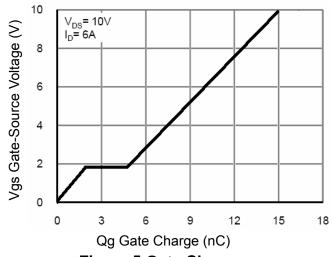


Figure 5 Gate Charge

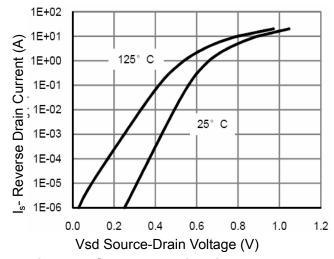


Figure 6 Source- Drain Diode Forward



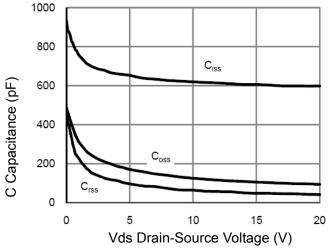


Figure 7 Capacitance vs Vds

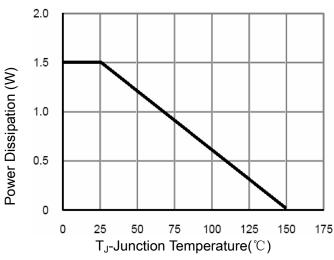


Figure 9 Power De-rating

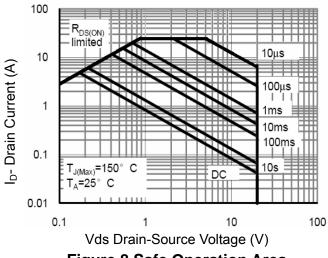


Figure 8 Safe Operation Area

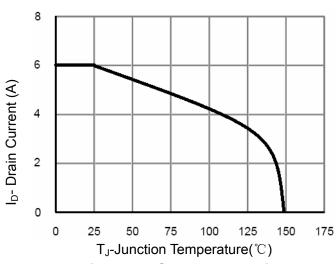
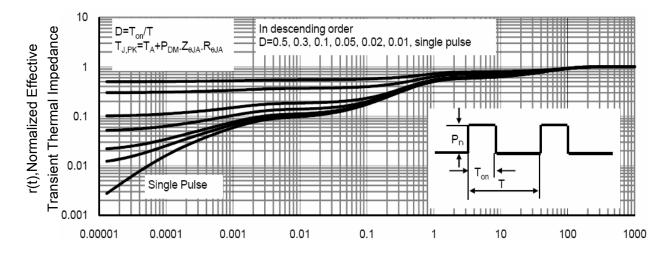


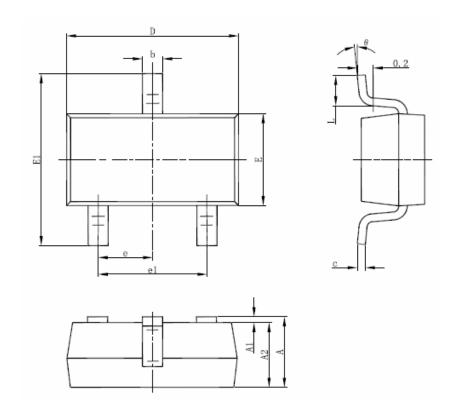
Figure 10 Current De-rating



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

SOT-23-3L Package Information



Sumb a l	Dimensions In	Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950	(BSC)	0.037(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact

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